

Amendments to the Specification

Change page 13, line 13 to page 14, line 2, as follows:

As shown in Fig. 7, Ti/Cu is deposited on the whole surfaces of the magnetic insulation substrates with sputtering to form plating seed layers 44 before the connecting conductors 14 and 16 are formed in the through holes 42 and 43, and the coil conductors 12a, 12b, 13a and 13b, and the connection terminals 15a and 15b are formed on the first and second principal surfaces. The plating seed layers 44 can alternatively formed with electroless plating. Instead of the sputtering method, vacuum deposition or CVD (chemical vapor deposition) may be used. It is preferred that the deposited layer has a sufficient adhesion to the ferrite substrate 1. The conductive material may be any appropriate material with electrical conductivity. In the embodiment, titanium is used as an adhesive layer to obtain good adhesion, and other materials such as Cr, W, Nb, and Ta may be used. The copper layer is a seed layer to be plated in the ~~next~~ next step of electroplating, and nickel or gold may be used instead of copper. In the embodiment, Ti/Cu is used considering ease of machining in the later steps.

Change page 24, lines 11-25, as follows:

Referring to Fig. 20, in order to provide electrical conductivity, Ti/Cu is deposited on the whole surface of the substrate with sputtering to form plating seed layers 94. The plating seed layers 94 can alternatively be formed with electroless plating. Instead of the sputtering method, vacuum deposition or CVD (chemical vapor deposition) may be used. It is preferred that the deposited layer has a sufficient adhesion to the substrate. The conductive material may be any appropriate material with electrical conductivity. In the embodiment, titanium is used as an adhesive layer to obtain good adhesion, and other materials such as Cr, W, Nb, and Ta may be used. The copper layer is a seed layer to

be plated in the ~~next~~ next step of electroplating, and nickel or gold may be used instead of copper. In the embodiment, Ti/Cu is used considering ease of machining in the later steps.